

Atty. Docket No. PLA31180/DBE/US
Serial No: 10/750,248

Claims

Please amend the claims as follows:

1-8. (Withdrawn)

9. (Currently amended) A method for removing polymers generated during etching processes, comprising the steps of:

removing the polymers by using an inorganic compound including DIW, H₂SO₄, H₂O₂ and HF;

forming a protective oxide film on a metal line, a via hole or a pad open area by using H₂O₂; and

protecting the metal line, the via hole or the pad open area by the protective oxide film while removing the polymers by using HF.

wherein DIW occupies by volume about 70.5% to about 80.5% of the total volume of DIW, H₂SO₄, H₂O₂ and HF, H₂SO₄ occupies by volume about 6.5% to about 8.5% of the total volume of DIW, H₂SO₄, H₂O₂ and HF, H₂O₂ occupies by volume about 15% to about 19% of the total volume of DIW, H₂SO₄, H₂O₂ and HF, and HF occupies by volume about 50 PPM to about 150 PPM of the total volume of DIW, H₂SO₄, H₂O₂ and HF, and wherein the total volume % of DIW, H₂SO₄, H₂O₂ and HF is about 100 %.

10. (Canceled)

11. (Currently amended) The method of claim [[10]] 9, wherein DIW occupies by volume about 75.5% of the total volume of DIW, H₂SO₄, H₂O₂ and HF.

12. (Canceled)

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13. (Currently amended) The method of claim [[12]] 9, wherein H₂SO₄ occupies by volume about 7.5% of the total volume of DIW, H₂SO₄, H₂O₂ and HF.

14. (Canceled)

15. (Currently amended) The method of claim [[14]] 9, wherein H₂O₂ occupies by volume about 17% of the total volume of DIW, H₂SO₄, H₂O₂ and HF.

16. (Canceled)

17. (Withdrawn)